

TLE4966V-1K

In Plane Sensing with Vertical Dual Hall Effect Latch
for Automotive Applications

Technical Product Description

Revision 1.1, 2013-09-23

Edition 2013-09-23

**Published by
Infineon Technologies AG
81726 Munich, Germany**

**© 2013 Infineon Technologies AG
All Rights Reserved.**

Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

Revision History

Page or Item	Subjects (major changes since previous revision)
--------------	--

Revision 1.1, 2013-09-23

15	Parameter Bhys changed
----	------------------------

Trademarks of Infineon Technologies AG

AURIX™, C166™, CanPAK™, CIPOS™, CIPURSE™, EconoPACK™, CoolMOS™, CoolSET™, CORECONTROL™, CROSSAVE™, DAVE™, EasyPIM™, EconoBRIDGE™, EconoDUAL™, EconoPIM™, EiceDRIVER™, eupec™, FCOS™, HITFET™, HybridPACK™, I²RF™, ISOFACE™, IsoPACK™, MIPAQ™, ModSTACK™, my-d™, NovalithIC™, OptiMOS™, ORIGA™, PRIMARION™, PrimePACK™, PrimeSTACK™, PRO-SIL™, PROFET™, RASIC™, ReverSave™, SatRIC™, SIEGET™, SINDRION™, SIPMOS™, SmartLEWIS™, SOLID FLASH™, TEMPFET™, thinQ!™, TRENCHSTOP™, TriCore™.

Other Trademarks

Advance Design System™ (ADS) of Agilent Technologies, AMBA™, ARM™, MULTI-ICE™, KEIL™, PRIMECELL™, REALVIEW™, THUMB™, µVision™ of ARM Limited, UK. AUTOSAR™ is licensed by AUTOSAR development partnership. Bluetooth™ of Bluetooth SIG Inc. CAT-iq™ of DECT Forum. COLOSSUS™, FirstGPS™ of Trimble Navigation Ltd. EMV™ of EMVCo, LLC (Visa Holdings Inc.). EPCOS™ of Epcos AG. FLEXGO™ of Microsoft Corporation. FlexRay™ is licensed by FlexRay Consortium. HYPERTERMINAL™ of Hilgraeve Incorporated. IEC™ of Commission Electrotechnique Internationale. IrDA™ of Infrared Data Association Corporation. ISO™ of INTERNATIONAL ORGANIZATION FOR STANDARDIZATION. MATLAB™ of MathWorks, Inc. MAXIM™ of Maxim Integrated Products, Inc. MICROTEC™, NUCLEUS™ of Mentor Graphics Corporation. Mifare™ of NXP. MIPI™ of MIPI Alliance, Inc. MIPS™ of MIPS Technologies, Inc., USA. muRata™ of MURATA MANUFACTURING CO., MICROWAVE OFFICE™ (MWO) of Applied Wave Research Inc., OmniVision™ of OmniVision Technologies, Inc. Openwave™ Openwave Systems Inc. RED HAT™ Red Hat, Inc. RFMD™ RF Micro Devices, Inc. SIRIUS™ of Sirius Satellite Radio Inc. SOLARIS™ of Sun Microsystems, Inc. SPANSION™ of Spansion LLC Ltd. Symbian™ of Symbian Software Limited. TAIYO YUDEN™ of Taiyo Yuden Co. TEAKLITE™ of CEVA, Inc. TEKTRONIX™ of Tektronix Inc. TOKO™ of TOKO KABUSHIKI KAISHA TA. UNIX™ of X/Open Company Limited. VERILOG™, PALLADIUM™ of Cadence Design Systems, Inc. VLYNQ™ of Texas Instruments Incorporated. VXWORKS™, WIND RIVER™ of WIND RIVER SYSTEMS, INC. ZETEX™ of Diodes Zetex Limited.

Last Trademarks Update 2011-02-24

Table of Contents

	Table of Contents	4
1	Product Description	5
1.1	Target Applications	5
1.2	Features	5
2	Functional Description	6
2.1	General	6
2.2	Pin Configuration (top view)	8
2.3	Block Diagram	9
2.4	Start-up Behavior	10
2.5	Application Circuit	11
3	Specification	12
3.1	Absolute Maximum Ratings	12
3.2	Operating Range	13
3.3	Electrical Characteristics	14
3.4	Magnetic Characteristics	15
4	Timing Diagrams for the Speed and Direction Output	16
5	Package Information	18

1 Product Description



1.1 Target Applications

The TLE4966V-1K is specifically designed to detect the rotation direction and the rotation speed of a pole wheel. The sensing direction is **in-plane** to the sensor surface. Even at high distances to the hall elements the direction will be detected correctly.



Figure 1-1 Image of TLE4966V in the PG-TSOP6-6-5 package

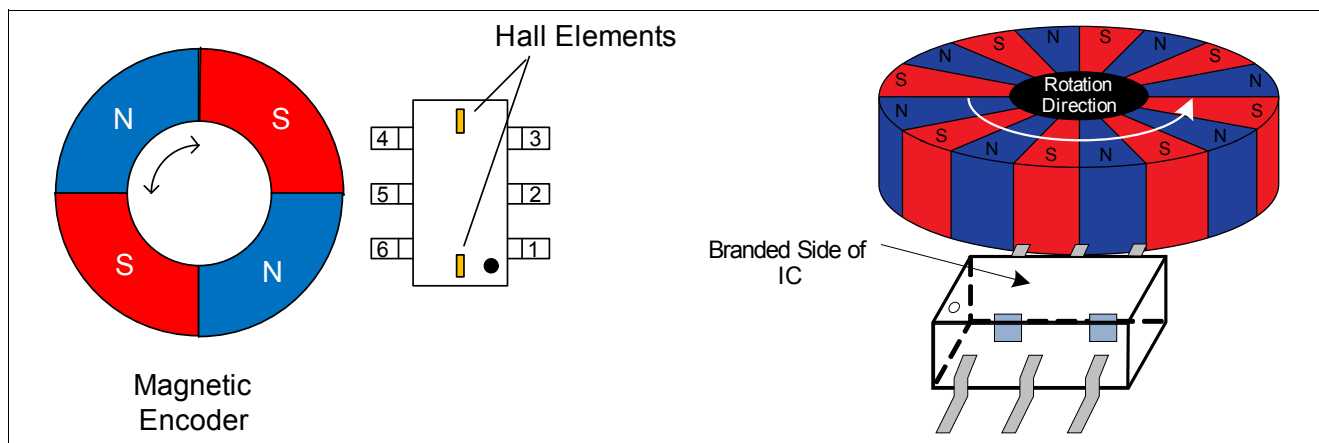


Figure 1-2 Target Application (top and side view): Sensing Direction parallel to target wheel

1.2 Features

- **In-Plane Sensing** for parallel mounting of magnetic encoder and sensor
- Low current consumption
- Direction Detection
- Speed output for index counting applications
- 3.5V to 32V operating supply voltage
- Operating from regulated power supply
- Reverse polarity protection (-18V)
- Over voltage capability up to 42 V without external resistor
- Output over current and over temperature protection
- High robustness to mechanical stress by Active Error Compensation
- Low drift of magnetic thresholds
- Low jitter (typ. 0.3us)
- SMD package PG-TSOP6-6-5

Table 1-1 Ordering Information

Product Name	Product Type	Ordering Code	Package
TLE4966V	Dual Vertical Hall Latch	SP001102894	TSOP6-6-5

2 Functional Description

The TLE4966V-1K is specifically designed to detect the direction and rotational speed of a pole wheel as shown in [Figure 1-2](#).

2.1 General

The new Infineon Vertical Double Hall Switch TLE4966V-1K has integrated the functionality of detecting speed and direction of a rotating magnet, commonly known as pole wheel.

Note: Completely new is the in plane field direction which will be detected with the TLE4966V-1K shown in [Figure 2-1](#) which enables completely new application layouts.

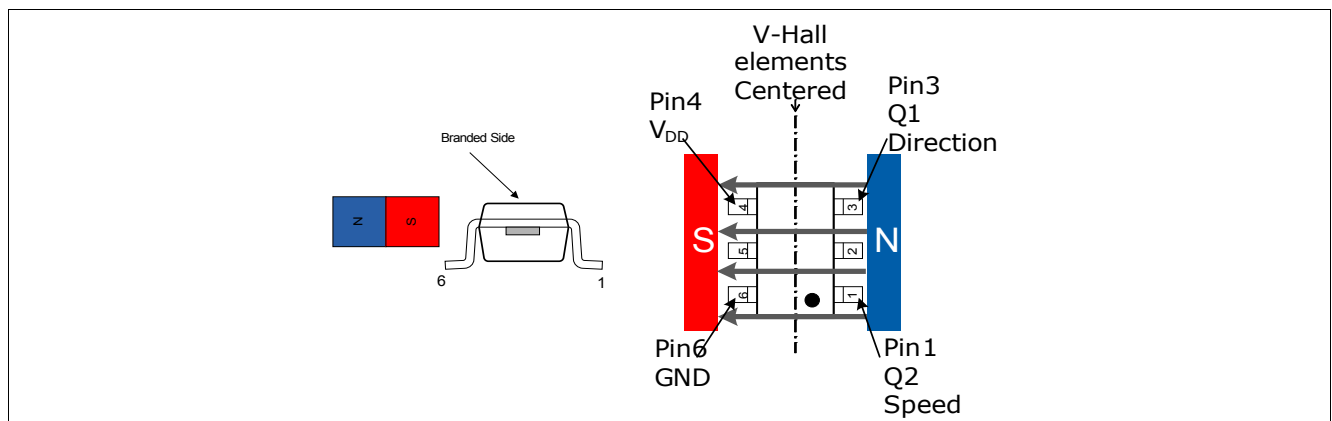


Figure 2-1 Target Application: Side view and top view for In-Plane Sensing

The sensor provides a speed output at Q2 with the status (high or low) corresponding to the magnetic field value. For positive magnetic fields (south pole) exceeding the threshold B_{OP} the output is low, whereas for negative magnetic fields (north pole) lower than B_{RP} the output switches to high. The output Q1 can be either high or low depending on the direction of rotation of the pole wheel. This direction information is calculated internally. (see [Table 2-2](#))

Designed in a new technology, this device offers high voltage capabilities with very small current consumption. The product can be operated from unregulated power supplies which offers our customers unique freedom of design for their system.

This product is AEC Q100 certified and enables our customers to build systems for the highest automotive quality requirements. The product has a TSOP6 package, which is RoHS compliant and fulfills the usual automotive environmental guidelines.

Application Examples are:

- Window lifter (index counting)
- Power closing (index counting)
- All applications with the need of speed and direction detection.

[Figure 2-2](#) and [Table 2-1](#) show the mapping of a pole wheel with the two corresponding output signals of the device.

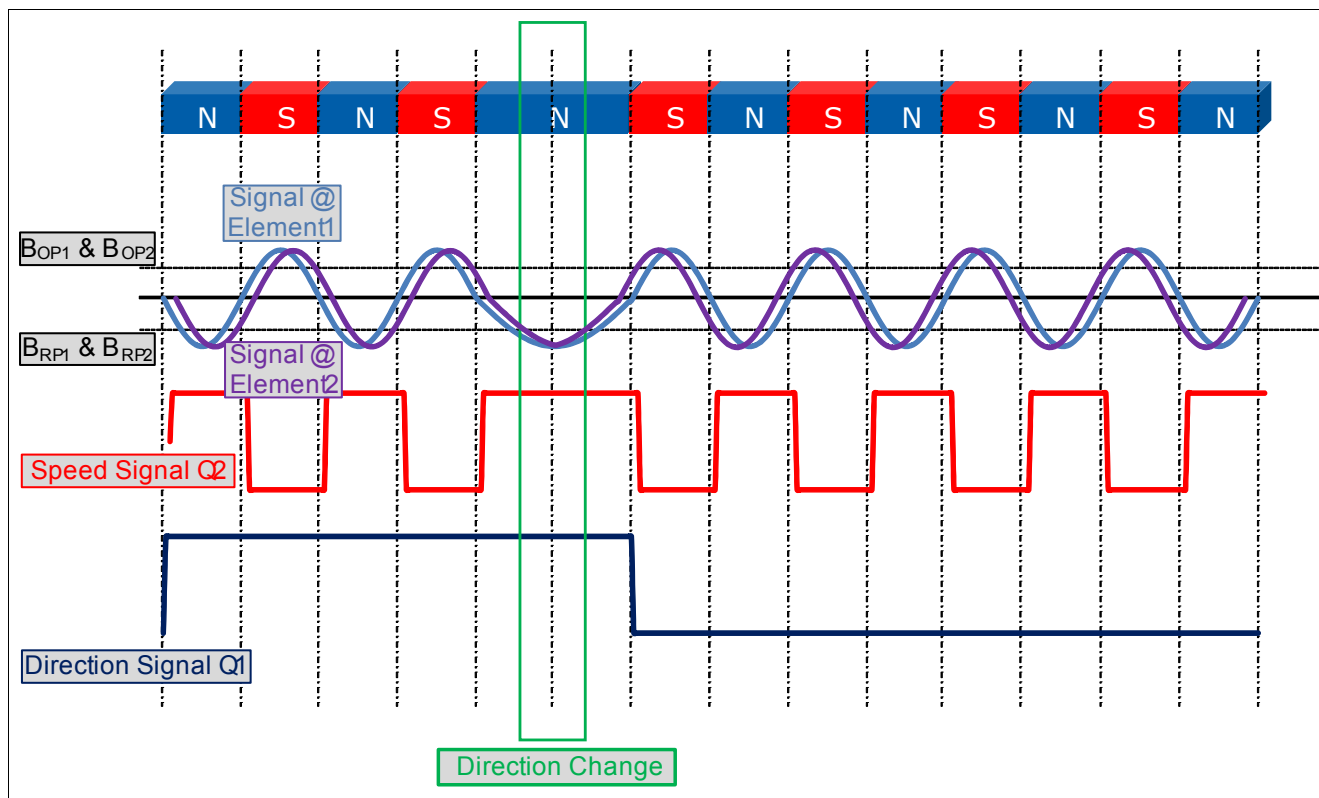


Figure 2-2 Magnetic field signal with the corresponding speed & direction output including the definition of the direction signal

Table 2-1 Output Pin Q1 Direction Signals

Rotation direction	State of direction output Q1
Counterclockwise	Low
Clockwise	High

2.2 Pin Configuration (top view)

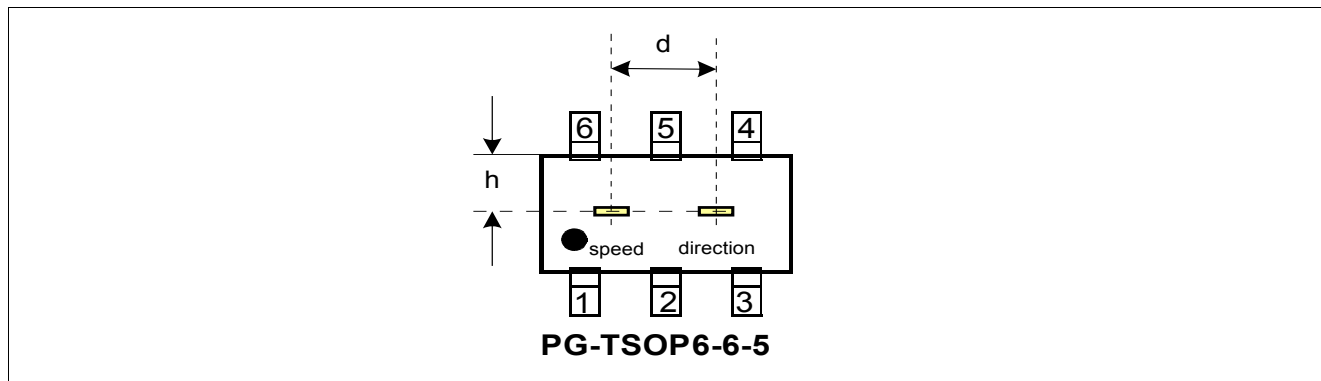


Figure 2-3 PG-TSOP6-6-5 Pin Configuration and sensitive area (d = 1.25mm) (see table 2-2)

Table 2-2 Pin Description PG-TSOP6-6-5

Pin No.	Symbol	Function
1	Q2	Speed
2	GND	Recommended connection to GND
3	Q1	Direction
4	V_{DD}	Supply voltage
5	GND	Recommended connection to GND
6	GND	Ground

2.3 Block Diagram

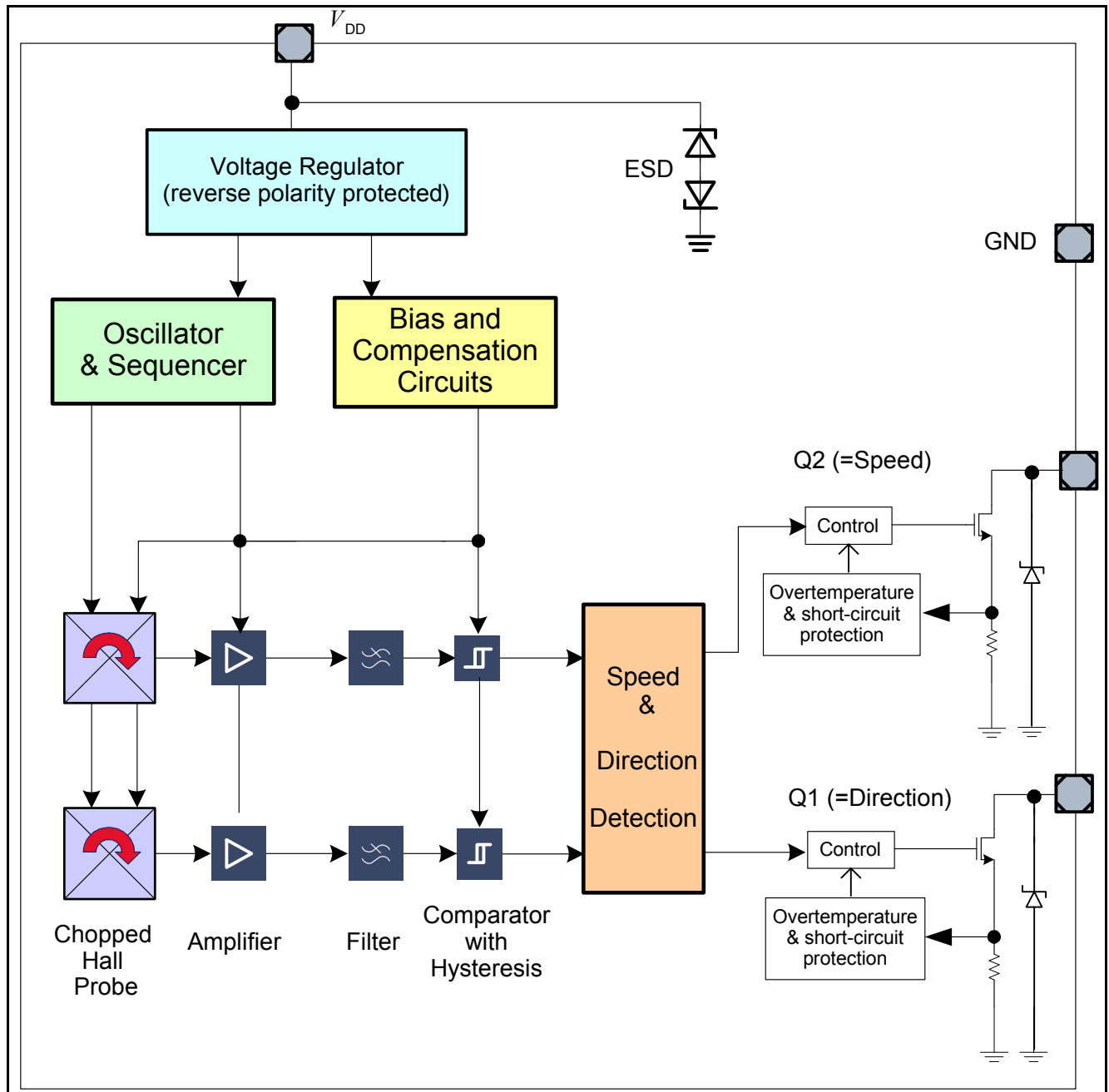


Figure 2-4 Functional Block Diagram of the TLE4966V-1K

The chopped Dual Hall IC switch comprises a Hall probe, bias generator, compensation circuits, oscillator and output transistor.

The bias generator provides currents for the Hall probe and the active circuits. Compensation circuits stabilize the temperature behavior and reduce influence of technology variations.

The active error compensations (chopping technique) rejects offsets in the signal path. Therefore the influence of mechanical stress to the Hall elements caused by molding and soldering processes and other thermal stress in the package is minimized. The chopped measurement principle together with the threshold generator and the comparator ensures highly accurate and temperature stable magnetic thresholds. The output transistor has an integrated over current and over temperature protection to prevent the device from destruction.

2.4 Start-up Behavior

The magnetic threshold exhibit a hysteresis $B_{\text{hys}} = B_{\text{op}} - B_{\text{rp}}$. In case of a power-on with a magnetic field B within hysteresis ($B_{\text{rp}} < B < B_{\text{op}}$) the output of the sensor is set to the pull up voltage level " V_Q " per default. After the first crossing of B_{op} or B_{rp} of the magnetic field the internal decision logic is set to the corresponding magnetic input value.

V_{DDA} is the internal supply voltage which is following the external supply voltage V_{DD} .

This means for $B > B_{\text{op}}$ the output is switching for $B > B_{\text{rp}}$ and $B_{\text{op}} > B > B_{\text{rp}}$ the output stays at V_Q

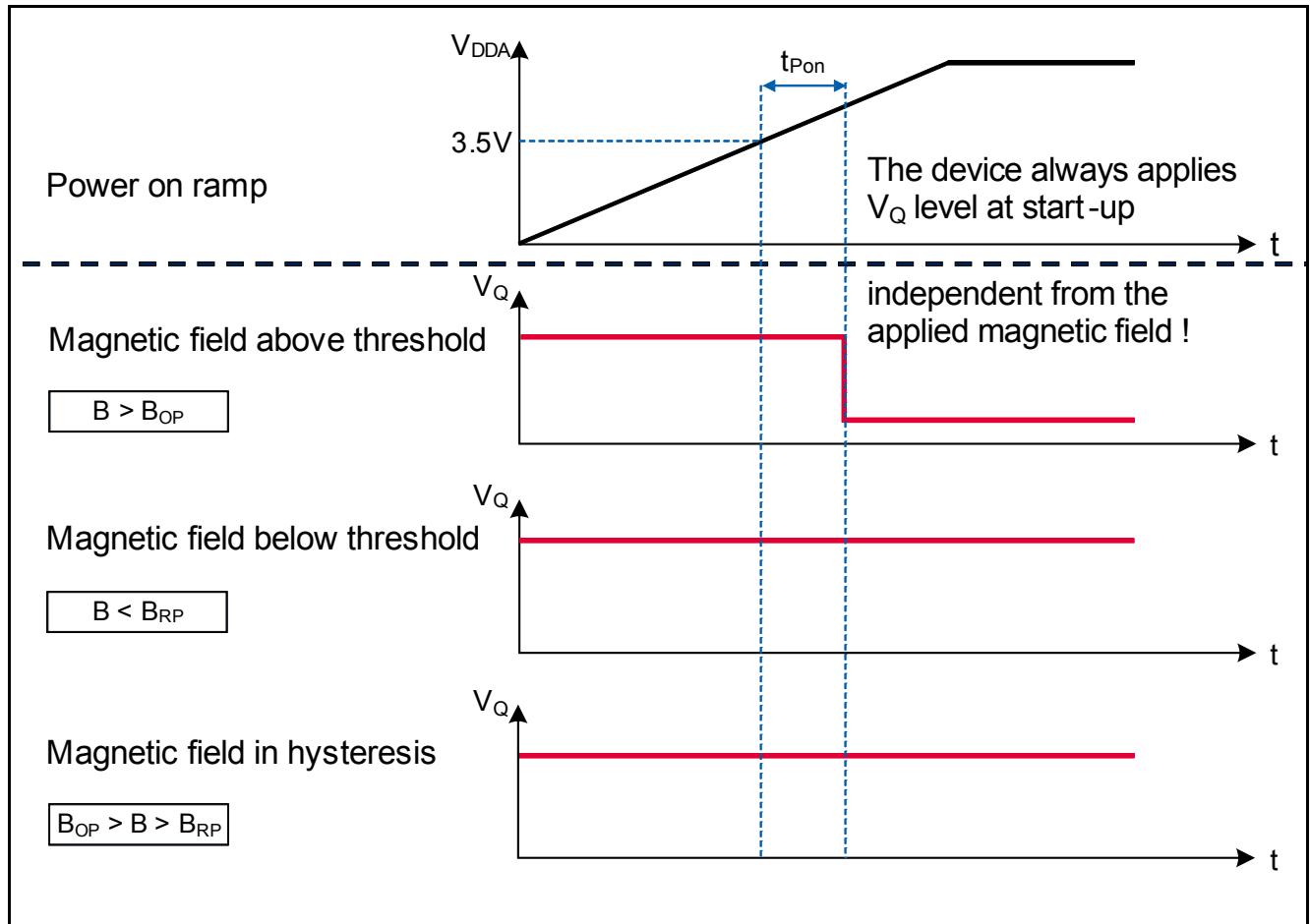


Figure 2-5 Start-up behavior of the at different magnetic start conditions

2.5 Application Circuit

The **Figure 2-6** below shows the basic option of an application circuit. The Resistor R_Q has to be in a dimension to match the applied V_S to keep I_Q limited to the operating range of maximal 10mA. For example: $V_S = 12V$, $I_Q < 10mA \rightarrow R = 12V / 0.01A = 1.2k\Omega \rightarrow R_Q > 1.2k\Omega$.

In **Figure 2-7** additional ESD Diodes are optional the achieve an increased ESD robustness at the Q pins. Furthermore with the (optional) 47nF between V_{DD} and GND a high system level robustness is achieved.

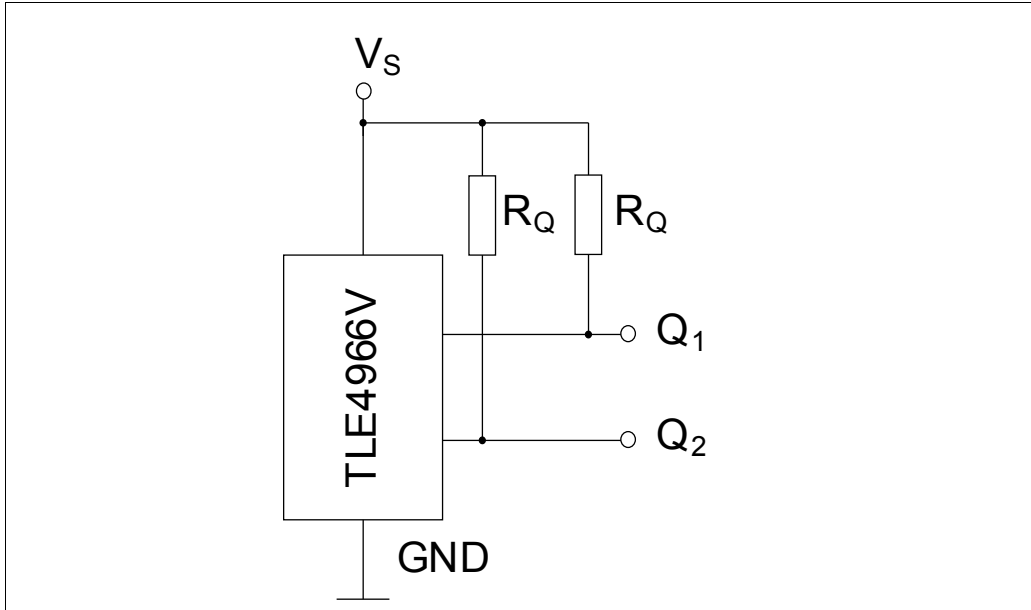


Figure 2-6 Basic Application Circuit

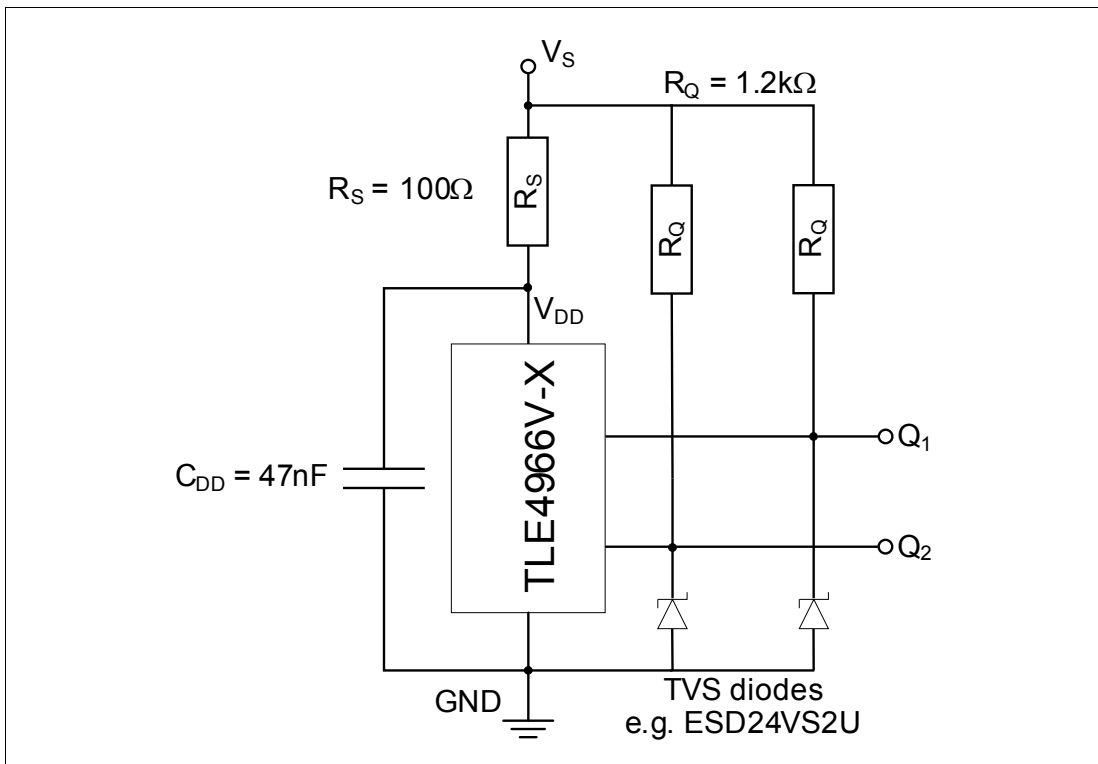


Figure 2-7 Enhanced Application Circuit for very high ESD robustness on system level

3 Specification

3.1 Absolute Maximum Ratings

Table 3-1 Absolute Maximum Rating Parameters

Parameter	Symbol	Limit Values		Unit	Note / Test Condition
		Min.	Max.		
Supply voltage	V_{DD}	-18	32 42	V	10h, no external resistor required
Output voltage	V_Q	-0.5	32	V	
Reverse output current	I_Q	-35		mA	
Junction temperature	T_J	-40	155 165 175 195	°C	for 2000h (not additive) for 1000h (not additive) for 168h (not additive) for 3 x 1h (additive)
Storage temperature	T_S	-40	150	°C	
Thermal resistance Junction ambient	R_{thJA}		200	K/W	for PG-TSOP6-6-5
Thermal resistance Junction lead	R_{thJL}		100	K/W	for PG-TSOP6-6-5

Attention: Stresses above the max. values listed here may cause permanent damage to the device.
Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit.

Calculation of the dissipated power P_{DIS} and junction temperature T_J of the chip in TSOP6:

e.g for: $V_{DD} = 12\text{ V}$, $I_S = 10\text{ mA}$, $V_{QSAT} = 0.5\text{ V}$, $I_Q = 10\text{ mA}$

Power dissipation: $P_{DIS} = 12\text{ V} \times 10\text{ mA} + 2 \times (0.5\text{ V} \times 10\text{ mA}) = 120\text{ mW} + 10\text{ mW} = 130\text{ mW}$

Temperature $\Delta T = R_{thJA} \times P_{DIS} = 200\text{ K/W} \times 130\text{ mW} = 26\text{ K}$

For $T_A = 100^\circ\text{C}$: $T_J = T_A + \Delta T = 100^\circ\text{C} + 26\text{ K} = 126^\circ\text{C}$

Table 3-2 ESD Protection¹⁾ ($T_A = 25^\circ\text{C}$)

Parameter	Symbol	Limit Values		Unit	Note / Test Condition
		Min.	Max.		
ESD voltage (HBM) ²⁾	V_{ESD}	-2	+2	kV	$R = 1.5\text{ k}\Omega$, $C = 100\text{ pF}$
System level test		-6	+6		Figure 2.7 ³⁾

1) Characterization of ESD is carried out on a sample basis.

2) Human Body Model (HBM) tests according to EIA/JESD22-A114

3) Gun test (2k Ω /330pF or 330 Ω /150pF) according to ISO 10605-2008

3.2 Operating Range

Attention: The following operating conditions must not be exceeded in order to ensure correct operation of the TLE4966V-1K. All parameters specified in the following sections refer to these operating conditions unless otherwise mentioned.

Table 3-3 Operating Conditions Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply voltage	V_{DD}	3.5		32 ¹⁾	V	
Output voltage	V_Q	-0.3		32	V	
Junction temperature	T_j	-40		150	°C	
Output current	I_Q	0		10	mA	
Magnetic signal input frequency ²⁾	f_{mag}	0		5	kHz	

1) Latch-up test with factor 1.5 is not covered. Please see max ratings also.

2) For operation at the maximum switching frequency the magnetic input signal must be 1.4 times higher than for static fields. This is due to the -3dB corner frequency of the internal low-pass filter in the signal path.

3.3 Electrical Characteristics

Table 3-4 General Electrical Characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply current	I_S	3.9	5.8	7.3	mA	
Reverse current	I_{SR}	-	0.05	1	mA	for $V_{DD} = -18V$
Output saturation voltage	V_{QSAT}	-	0.2	0.5	V	$I_Q = 10mA$
Output leakage current	I_{QLEAK}	-	-	5.0	μA	$T=150^\circ C$, 12V
Output current limitation	I_{QLIMIT}	20	30	40	mA	internally limited & thermal shutdown
Output fall time ¹⁾	t_f	0.1	0.2	1	μs	1.2k Ω^2 / 50pF, see Figure 4-1
Output rise time ¹⁾	t_r	0.1	0.2	1	μs	1.2k Ω^2 / 50pF, see Figure 4-1
Output jitter ³⁾¹⁾	t_{QJ}		0.3	1	μs	For square wave signal with 1kHz
Effective noise value of the magnetic switching points ⁴⁾¹⁾	B_{Neff}		45		μT_{RMS}	
Delay time ⁵⁾¹⁾	t_d	8	20	30	μs	see Figure 4-1
Signal Count Delay ¹⁾	t_{dc}	50	400	1000	ns	1.2k Ω /50pF @ $V_Q=12V$, Direction before Speed Signal, 50% to 50%
Power-on time ⁶⁾¹⁾	t_{PON}	48	84	120	μs	$V_{DD} = 3.5 V$, $B \leq B_{RP} - 0.5 mT$ or $B \geq B_{OP} + 0.5 mT$
Chopper frequency ¹⁾	f_{OSC}		1300		kHz	

1) Not subject to production test, verified by design/characterization

2) Current limitation has to be taken into consideration for $V_S > 12V$ in order not to exceed 10mA

3) Output jitter is the 1σ value of the output switching distribution.

4) The magnetic noise is normal distributed and can be assumed as nearly independent to frequency without sampling noise or digital noise effects. The typical value represents a the rms-value and corresponds therefore to a 1σ probability of normal distribution. Consequently a 3σ value corresponds to 0.3% probability of appearance.

5) Systematic delay between magnetic threshold reached and output switching.

6) Time from applying $V_{DD} = 3.0 V$ to the sensor until the output is valid.

3.4 Magnetic Characteristics

Table 3-5 Magnetic Characteristics

Parameter	Symbol	T (°C)	Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Operating point	B _{OP}	-40	1.1	2.8	4.5	mT	
		25	0.9	2.5	4.1		
		150	0.4	1.9	3.3		
Release point	B _{RP}	-40	-4.5	-2.8	-1.1	mT	
		25	-4.1	-2.5	-0.9		
		150	-3.3	-1.9	-0.4		
Hysteresis	B _{Hys}	-40	3.6	5.3	7.4	mT	
		25	3.4	5.0	6.8		
		150	2.5	3.7	5.2		
Magnetic Matching	B _{Match}		-1.0		+1.0	mT	for (Bop1 - Bop2) and (Brp1 - Brp2); -40..125°C
			-1.5		+1.5		-40..150°C
Magnetic Offset	B _{Off}		-1.0		+1.0	mT	(Bop + Brp) / 2; -40..125°C
			-1.5		+1.5	mt	(Bop + Brp) / 2; -40..150°C
Temperature Compensation ¹⁾	TC			-1700		ppm/K	ferrite magnet

1) Not subject to production test, verified by design/characterization

4 Timing Diagrams for the Speed and Direction Output

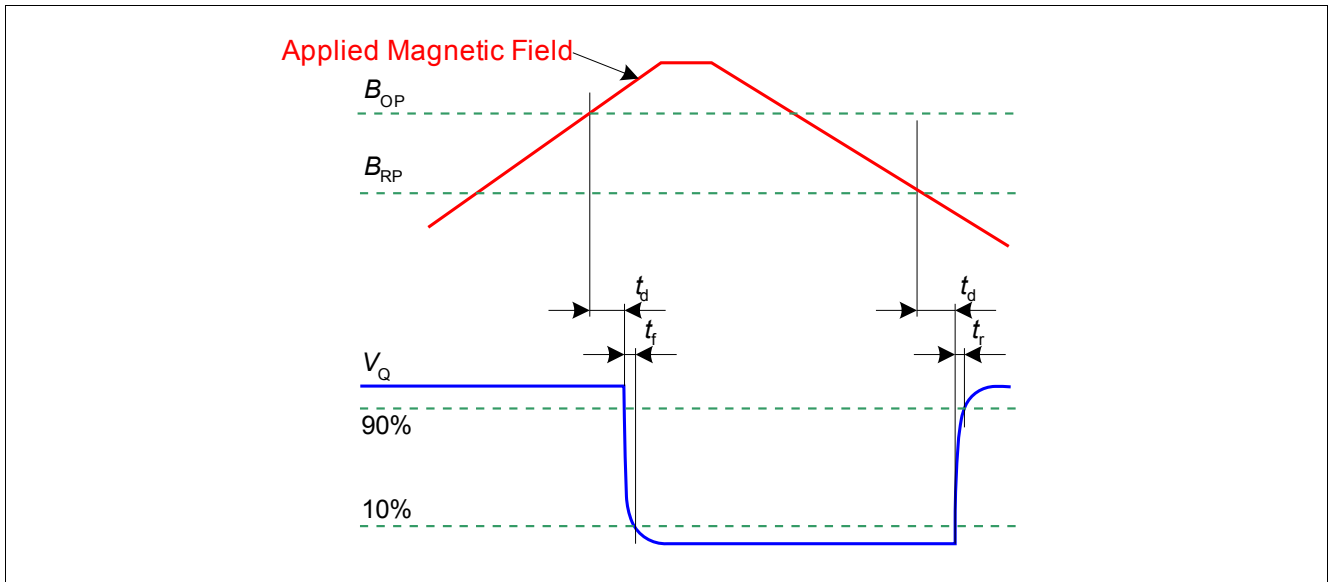


Figure 4-1 Timing Diagram TLE4966V

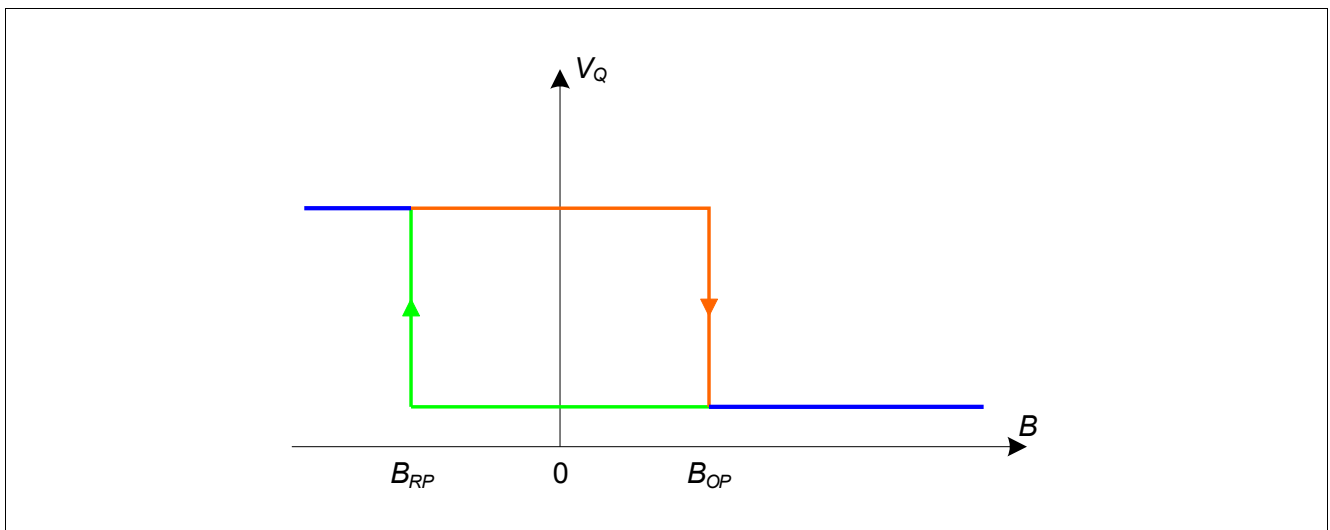


Figure 4-2 TLE4966V - Output Voltage Signal over applied magnetic Field

Timing Diagrams for the Speed and Direction Output

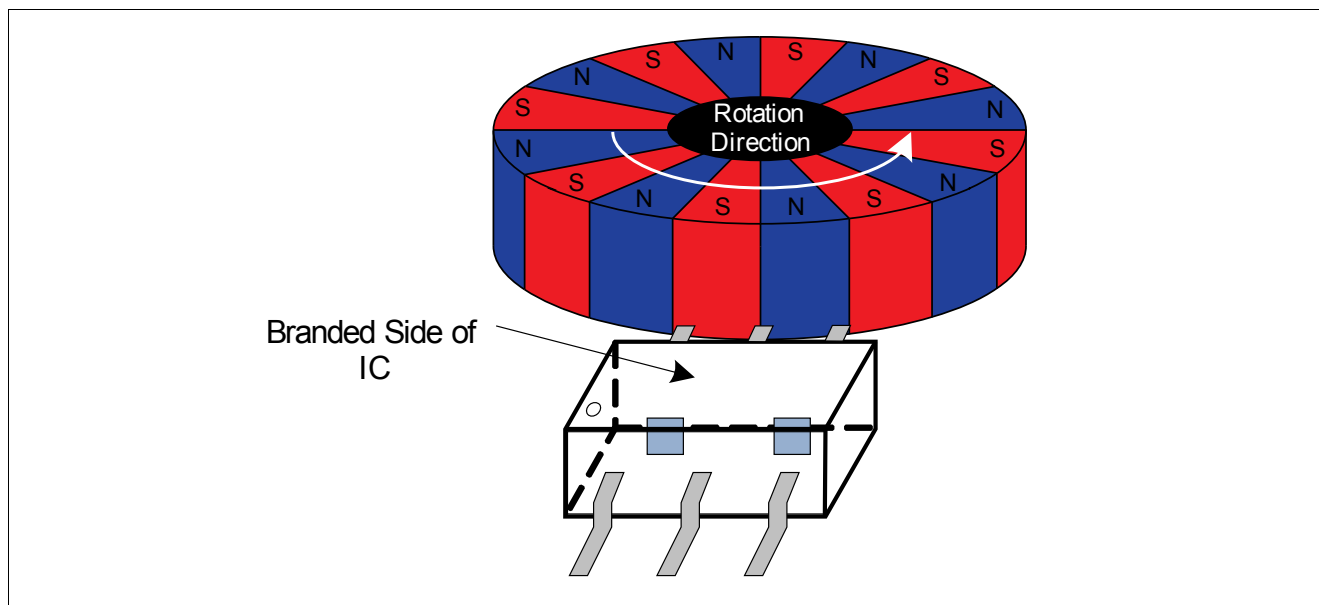


Figure 4-3 TLE4966V - Definition of the direction signal

Table 4-1 Output Pin Q1 Direction Signals

Rotation direction	State of direction output Q1
Counterclockwise	Low
Clockwise	High

5 Package Information

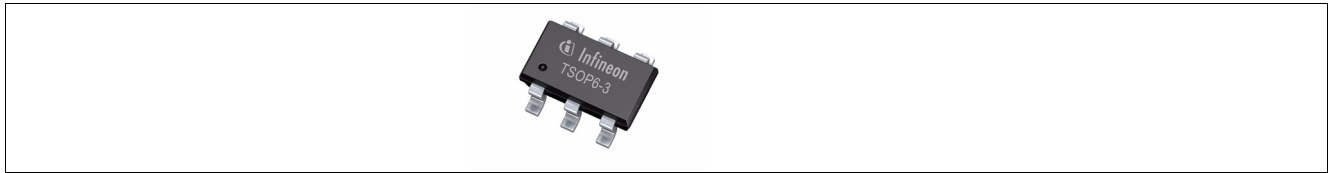


Figure 5-1 Image of TLE4966V in the PG-TSOP6-6-5 package

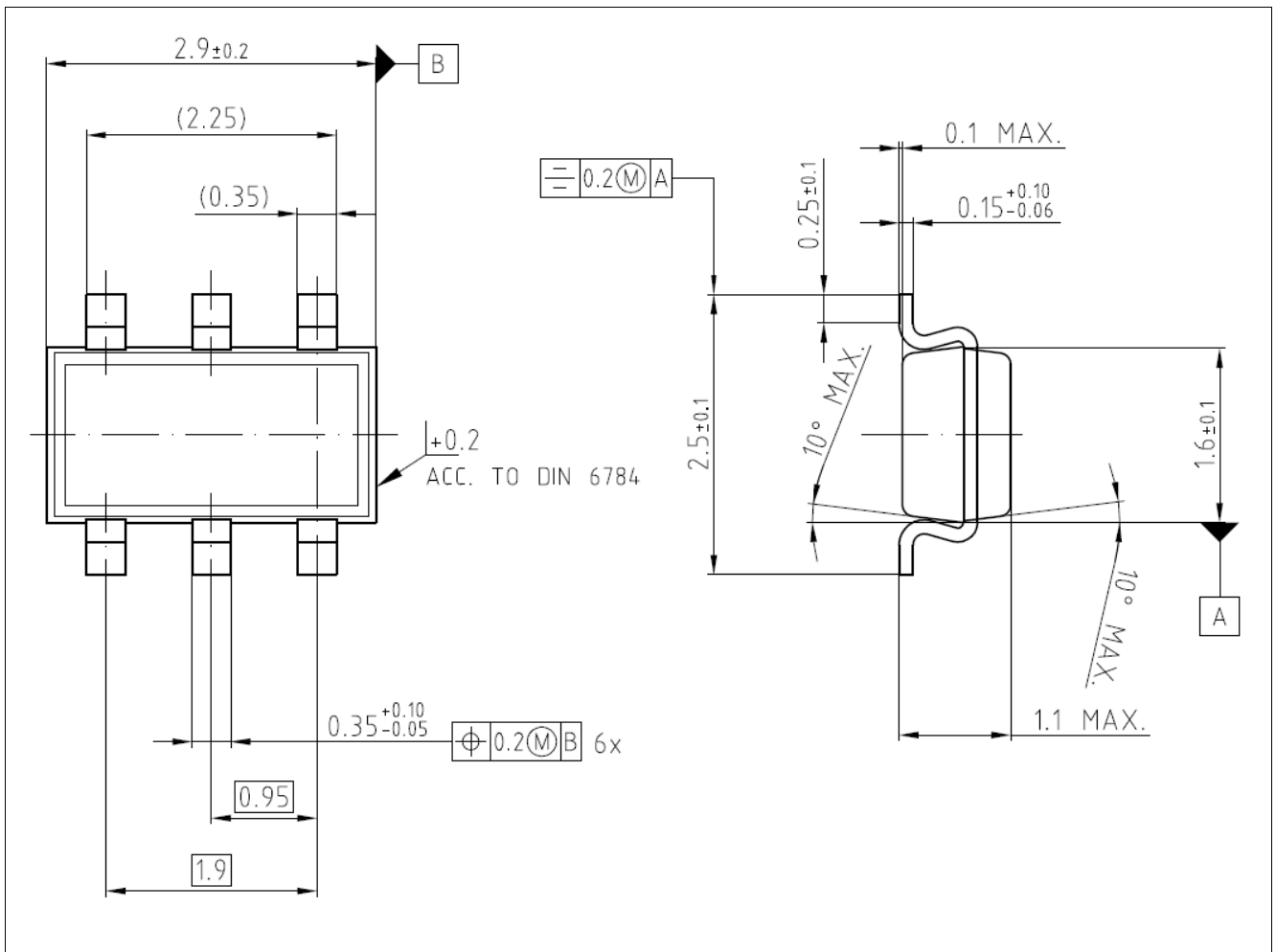


Figure 5-2 PG-TSOP6-6-5 Package Outline (All dimensions in mm)

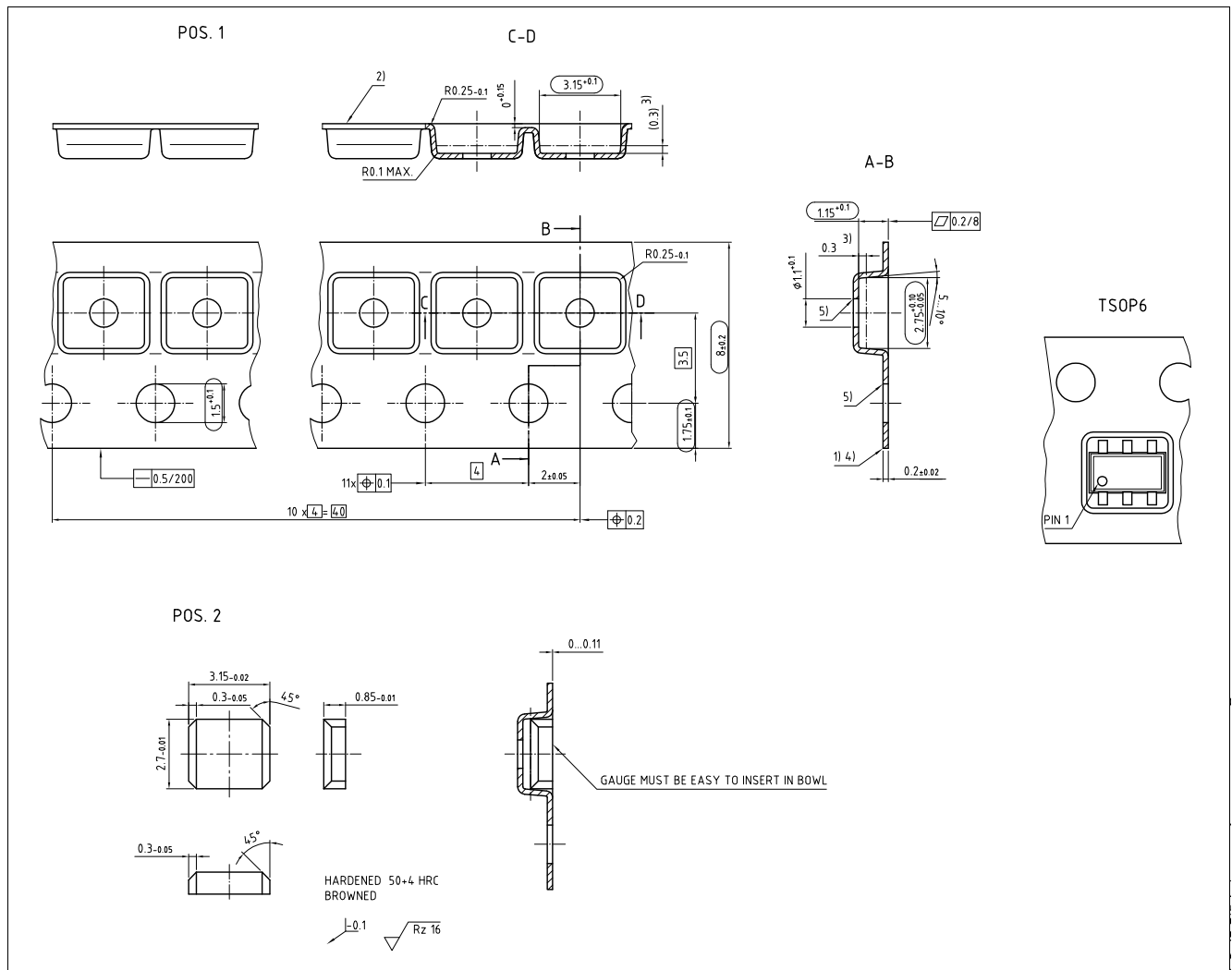


Figure 5-3 PG-TSOP6-6-5 Packing (All dimensions in mm)

The sensitive elements are placed in an optimized distance (d) to guarantee the direction detection. To compensate package stress the sensitive elements are placed in the middle of the package (h).

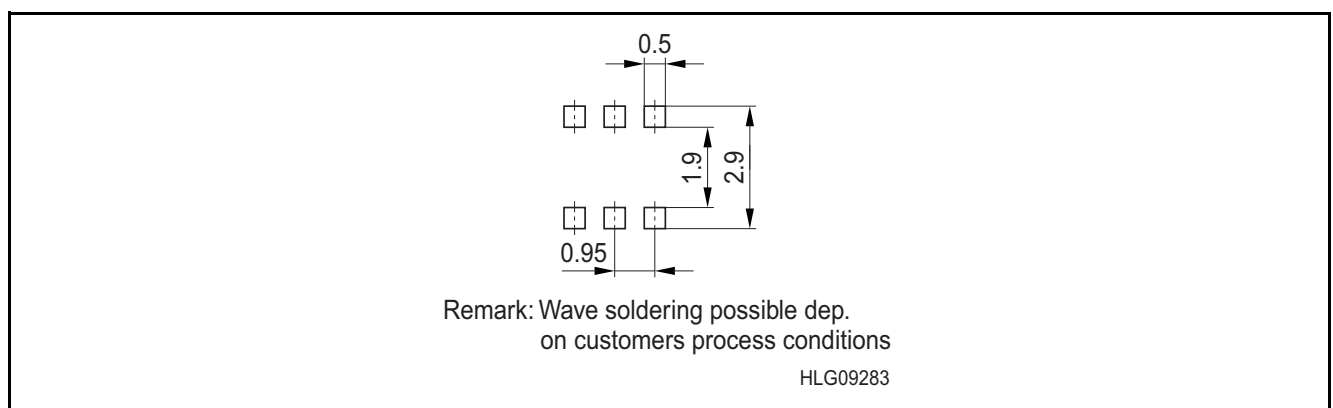


Figure 5-4 Footprint of PG-TSOP-6-6-5

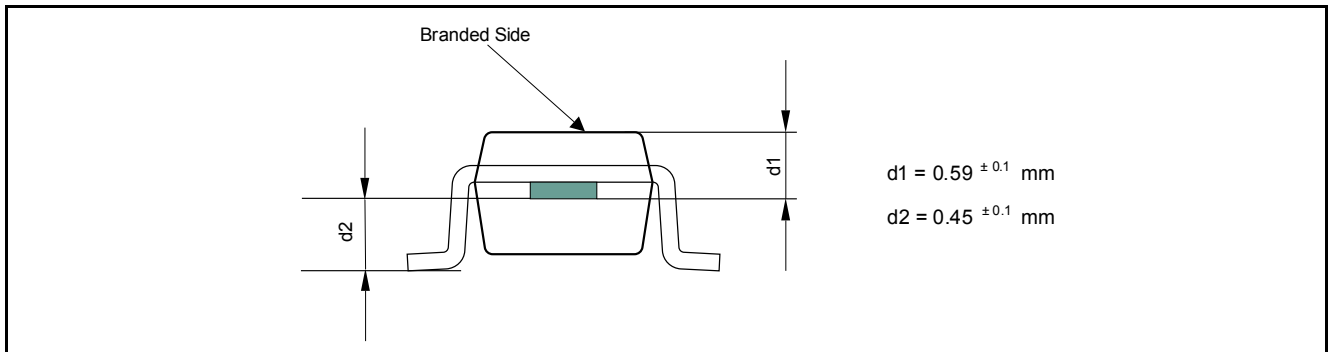


Figure 5-5 Distance between chip and package

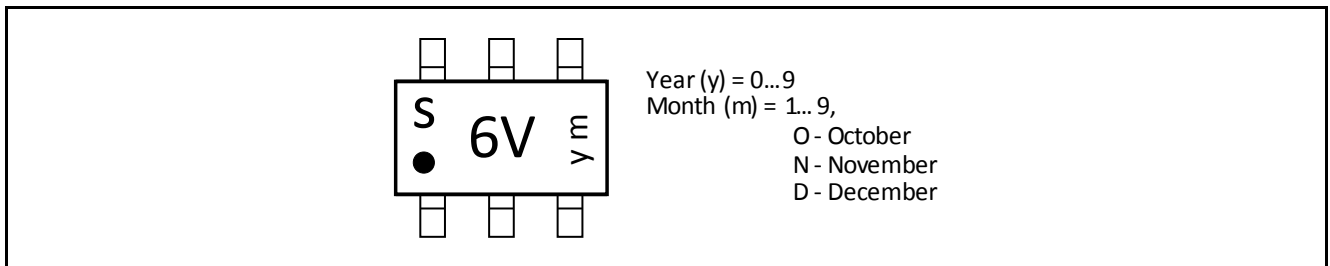


Figure 5-6 Marking of TLE4966V-1K

www.infineon.com